NOTES:
1. MATERIAL:
   CONTACT: BRASS, 50μ" Min. NICKEL UNDERPLATING.
   GOLD PLATING ON CONTACT AREA AND ON SOLDER AREA. (DETAIL SEE TABLE)
   PEG: BRASS, 50μ" Min. NICKEL UNDERPLATING,
       MATTE-Tin 100μ" Min OVER NICKEL.
   HOUSING: LCP, UL-94V0
2. ROHS, HF COMPLIANT.
3. ELECTRICAL PERFORMANCE
   CONTACT RESISTANCE: 55mΩ MAX. PER CONTACT
   INSULATION RESISTANCE: 500mΩ MIN
4. MECHANICAL PERFORMANCE
   DURABILITY: 50 CYCLES
   MATING AND UNMATING FORCE: 2.3Kgf MAX
5. IR REFLOW TEMPERATURE: 250°C ±10°C FOR 10 SECONDS MAX.
6. PRODUCT NUMBER NOTE: AAA-PCI-***-***-*

PACKING DIRECTION
TYPE SERIAL NUMBER
Κ: LEAD FREE/P: HALOGEN FREE
PRODUCT SERIAL NUMBER
PRODUCT TYPE
FINISHED PRODUCT
Board CONNECTOR
CONNECTOR

7. DATE CODE NOTE:
   XXXXXX
   Date
   Week
   Year
MINI PCI EXPRESS MODULE BOARD LAYOUT

GENERAL TOLERANCES
UNLESS SPECIFIED

SEE TABLE

PART NO.

MINI PCI EXPRESS 9.0H 0.8PITCH 52P

AP-AAA-PCI-047

XU

SHEET 4 / 6 SCALE 2 / 1 REV 9K

TITLE

BARNEY

DWG NO.

CHECKED BY

RAYMOND

CUSTOMER DRAWING

UNIT

MM\(\text{[INCH]}\)
NOTES:
1. MATERIAL:
   1.1 CARRY TAPE: PS
   1.2 COVER TAPE: PET
   1.3 SHIPPING CARTON: CORRUGATED FIBER
2. DIMENSION:
   2.1 REEL: W=44.5, A=330
   2.2 SHIPPING CARTON: L=335, W=335, H=300 (INNER)
3. QUANTITY:
   3.1 PRIMARY PACKING: 350 PCS/REEL
   3.2 SECONDARY PACKING: 6 REELS/CARTON(2100PCS)
4. PEELING RESISTANCE: 20gf~120gf
5. PEELING SPEED: 300mm/minutes.
NOTES:
1. MATERIAL:
   1.1 CARRY TAPE: PS
   1.2 COVER TAPE: PET
   1.3 SHIPPING CARTON: CORRUGATED FIBER
2. DIMENSION:
   2.1 REEL: W=44.5, dA=330
   2.2 SHIPPING CARTON: L=335, W=335, H=320 (INNER)
3. QUANTITY:
   3.1 PRIMARY PACKING: 350 PCS/REEL
   3.2 SECONDARY PACKING: 6 REELS/CARTON (2100PCS)
4. PEELING RESISTANCE: 20gf~120gf.
5. PEELING SPEED: 300mm/minutes.